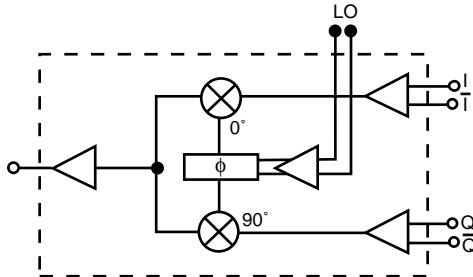


FEATURES

- **WIDE SUPPLY VOLTAGE RANGE:** 2.7 ~ 5.5 V
- **BROADBAND OPERATION:**
MODOUT = 100 - 400 MHz, I/Q = DC to 10 MHz
- **INTERNAL 90° PHASE SHIFTER**
- **POWER SAVE FUNCTION**
- **LOW POWER CONSUMPTION:** 16 mA Typ. @ 3 V
- **SMALL SSOP 16 PACKAGE**
- **TAPE AND REEL PACKAGING AVAILABLE**

FUNCTIONAL BLOCK DIAGRAM



DESCRIPTION

The UPC8105GR Silicon MMIC I/Q Modulator is manufactured using the NESAT III MMIC process. The NESAT III process produces transistors with f_T approaching 20 GHz. The device was designed for use in Digital Mobile Communications circuits such as 900 MHz Digital Cordless and Cellular Phones, WLAN and PCN/PCS Handset Transmitters.

NEC's stringent quality assurance and test procedures ensure the highest reliability and performance.

ELECTRICAL CHARACTERISTICS (TA = 25°C, Vcc = 3.0 V, VPS ≥ 1.8 V)

| PART NUMBER PACKAGE OUTLINE | | | UPC8105GR S16 (SSOP 16) | | |
|--------------------------------|---|----------|----------------------------|-----------|---------|
| SYMBOLS | PARAMETERS AND CONDITIONS | UNITS | MIN | TYP | MAX |
| Icc | Total Circuit Current (no signal) VPS ≥ 1.8 V VPS ≤ 1.0 V | mA µA | 10 0.1 | 16 0.1 | 21 5 |
| PMOD | Output Power - Modulator | dBm | -21 | -16.5 | -12 |
| LOLEAK | Local Oscillator Leakage | dBc | | -40 | -30 |
| ImR | Image Rejection | dBc | | -40 | -30 |
| IM3I/Q | I/Q 3rd Order Intermodulation Distortion | dBc | | -50 | |
| RLIN | I/Q LO Input Return Loss | dB | | 20 | |
| ZI/Q | Input Impedance I and Q Port | kΩ | | 20 | |
| T _{PS} (RISE) | Power Save Rise Time V _{PS} ≤ 1.0 V to V _{PS} ≥ 1.8V | µS | | 2 | 5 |
| T _{PS} (FALL) | Power Save Fall Time V _{PS} ≥ 1.8 V to V _{PS} ≤ 1.0 V | µS | | 2 | 5 |

ABSOLUTE MAXIMUM RATINGS¹ (TA = 25°C)

| SYMBOLS | PARAMETERS | UNITS | RATINGS |
|------------------|--------------------------------|-------|-------------|
| V _{CC} | Supply Voltage | V | 6.0 |
| V _{PS} | Enable Voltage for Power Save | V | 6.0 |
| P _D | Power Dissipation ² | mW | 530 |
| T _{OP} | Operating Temperature | °C | -40 to +85 |
| T _{STG} | Storage Temperature | °C | -65 to +150 |

Notes:

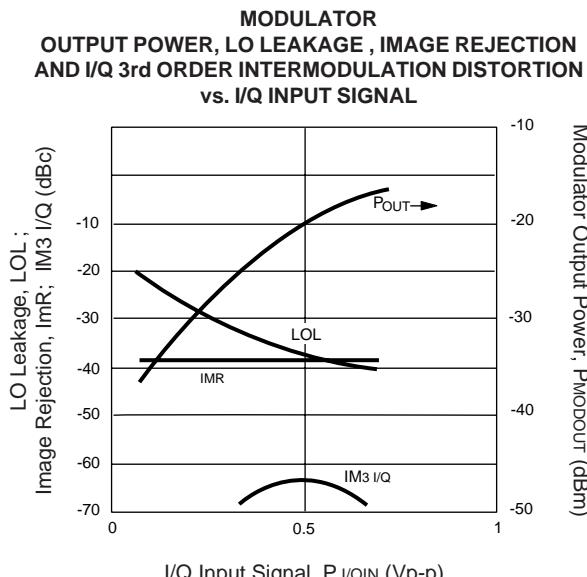
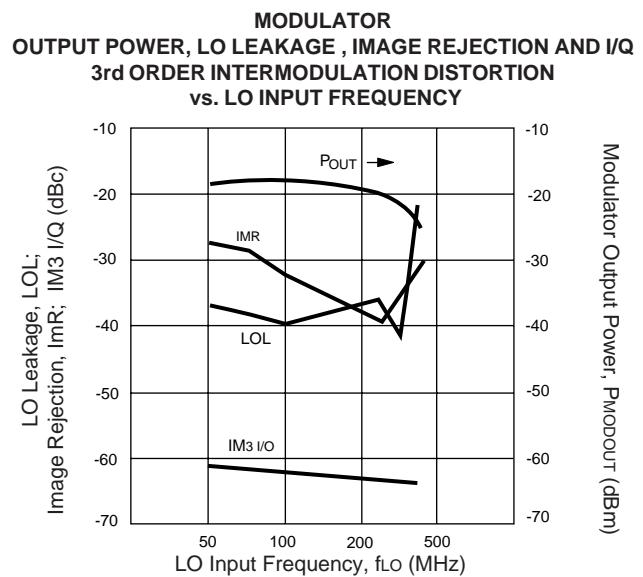
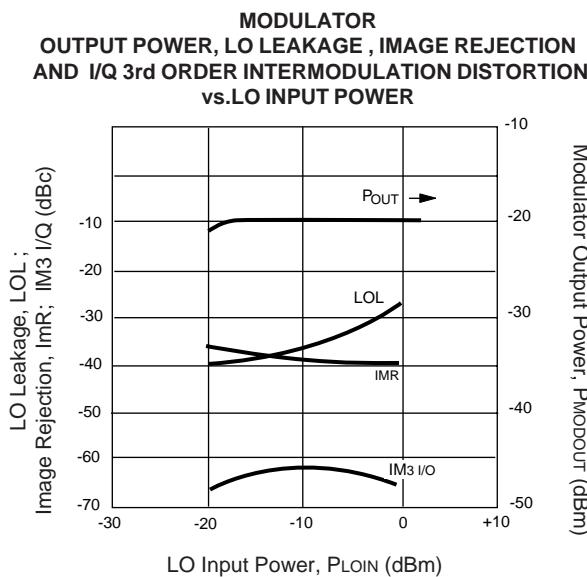
1. Operation in excess of any one of these parameters may result in permanent damage.
2. Mounted on a 50x50x1.6 mm double copper clad epoxy glass PWB (TA = 85°C).

RECOMMENDED OPERATING CONDITIONS

| SYMBOLS | PARAMETERS | UNITS | MIN | TYP | MAX |
|---------------------|----------------------------------|-------|-----|-----|-----|
| V _{CC} | Supply Voltage | V | 2.7 | 3.0 | 5.5 |
| T _{OP} | Operating Temperature | °C | -40 | +25 | +85 |
| f _{MODOUT} | Modulator Output Frequency | MHz | 100 | | 400 |
| f _{LOIN} | LO1 Input Frequency ¹ | MHz | 100 | | 400 |
| f _{I/QIN} | I/Q Input Frequency ² | MHz | DC | | 10 |

Notes:

1. P_{LOIN} = -10 dBm.
2. P_{I/QIN} = 600 mVp-p max.

TYPICAL PERFORMANCE CURVES (TA = 25°C, V_{CC} = V_{PS} = 3 V, I/Q DC Offset = I/Q DC Offset = 1.5 V,I/Q Input Signal = 500 mVp-p (Single-ended), P_{LOIN} = -10 dBm unless otherwise specified)

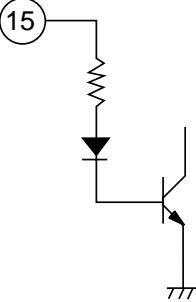
PIN FUNCTIONS

| Pin No. | Symbol | Supply Voltage | Pin Voltage | Description | Equivalent Circuit |
|---------|---------------|-----------------|-------------|--|--------------------|
| 1 | LOIN | — | 0 | LO input for the phase shifter. This input impedance is internally matched to $50\ \Omega$. | |
| 2 | LOIN (Bypass) | — | — | Bypass of the LO input. This pin is grounded through an internal capacitor. For a single-ended design this pin should be left open. | |
| 3 8 | GND | — | — | Connect to ground with minimum inductance. Track length should be kept as short as possible. | |
| 4 | I | $V_{CC}/2^{*2}$ | — | Input for I signal. This input impedance is larger than $20\ k\Omega$. The relationship between the amplitude and the DC bias of the input signal are as follows: | |
| 5 | \bar{I} | $V_{CC}/2^{*2}$ | — | Input for I signal. This input impedance is larger than $20\ k\Omega$. $V_{CC}/2$ biased DC signal should be input. | |
| 6 | \bar{Q} | $V_{CC}/2^{*2}$ | — | Input for Q signal. This input impedance is larger than $20\ k\Omega$. $V_{CC}/2$ biased DC signal should be input. | |
| 7 | Q | $V_{CC}/2^{*2}$ | — | Input for Q signal. This input impedance is larger than $20\ k\Omega$. The relationship between the amplitude and the DC bias of the input signal are as follows: | |
| 12 | MODout | — | — | Output from the modulator. This is emitter follower output. Connect approx. $15\ \Omega$ in series to match to $50\ \Omega$. | |

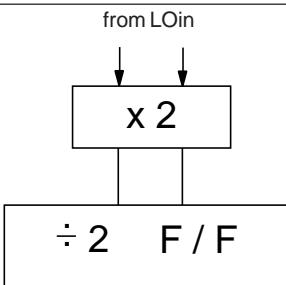
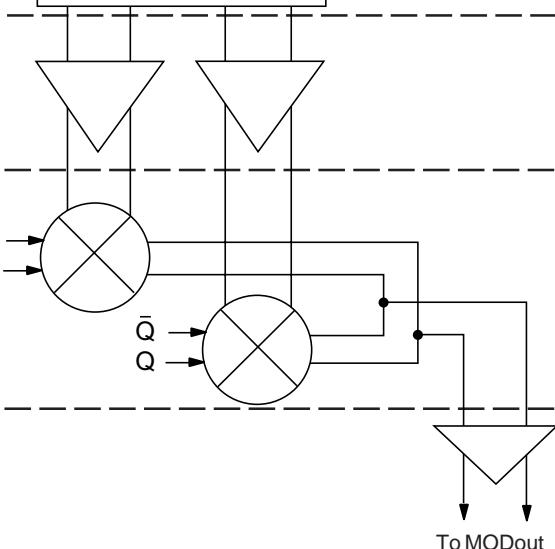
*1: In case I/Q input signals are single ended. I/Q signal inputs can be used either single-ended or differentially with proper terminations.

*2: $V_{CC}/2$ DC bias must be supplied to I, \bar{I} , Q, \bar{Q} .

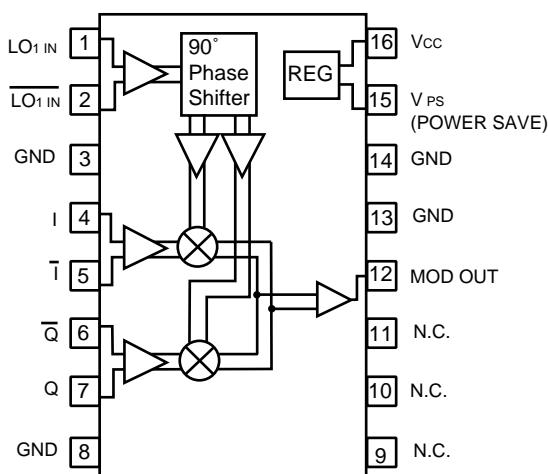
PIN FUNCTIONS

| Pin No. | Symbol | Supply Voltage | Pin Voltage | Description | Equivalent Circuit |
|---------|---------------------------------|-----------------|-------------|--|---|
| 13 | GND | 0 | — | Connect to the ground with minimum inductance. Track length should be kept as short as possible. | |
| 14 | | | | | |
| 15 | V _{PS} (Power Save) | V _{PS} | | Power save control pin can control the On/Sleep state with bias as follows: |  |
| 16 | V _{CC} | 2.7~5.5 | — | Supply voltage pin for the modulator. An internal regulator helps keep the device stable against temperature or V _{CC} variation. | |

MODULATOR INTERNAL FUNCTIONS

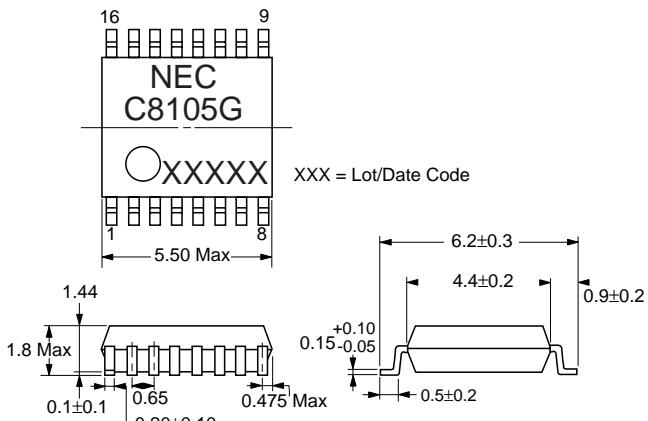
| Block | Function/Operation | Block Diagram |
|-------------------|---|--|
| 90° Phase Shifter | Input signal from LO is sent to a T-type flip-flop through a frequency doubler. The output signal from the T-type F/F is changed to the same frequency as LO input with a quadrature phase shift of 0°, 90°, 180°, or 270°. These circuits provide self phase correction for proper quadrature signals. |  |
| Buffer Amplifier | Buffer amplifiers for each phase signal are sent to each mixer. |  |
| Mixer | Each signal from the buffer amps is quadrature modulated with two double-balanced mixers. High accurate phase and amplitude inputs are realized to provide excellent image rejection. | |
| Adder | Output signal from each mixer is added and sent through a final amplifier stage to pin 16 for further off-chip filtering if necessary. | |

INTERNAL BLOCK DIAGRAM



OUTLINE DIMENSIONS (Units in mm)

PACKAGE OUTLINE SSOP 16



ORDERING INFORMATION

| PART NUMBER | QUANTITY |
|--------------|-----------|
| UPC8105GR-E1 | 2500/Reel |

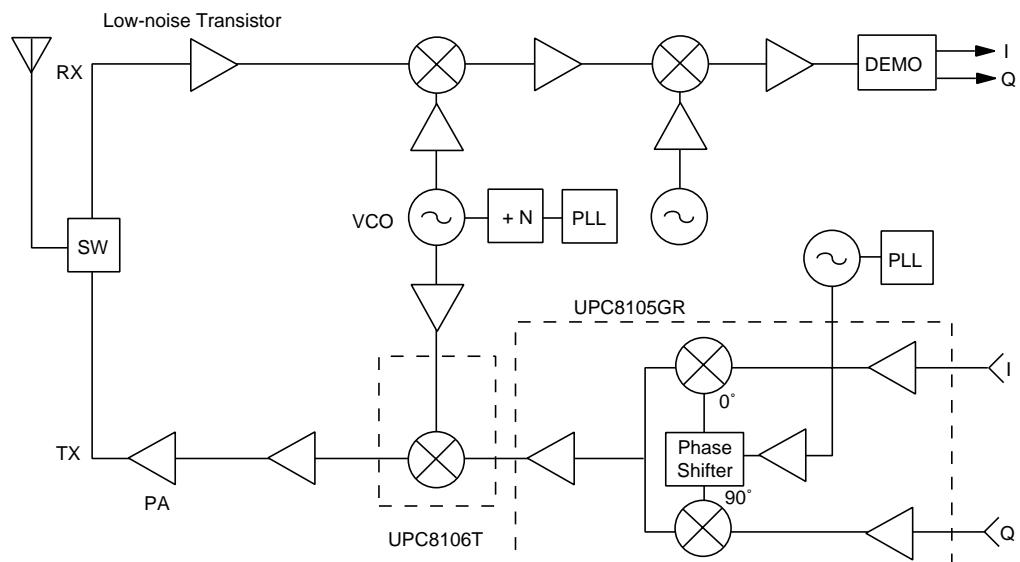
Note: Embossed Tape, 12 mm wide.

LEAD CONNECTIONS

| | |
|------------|----------------------|
| 1. LOIN | 9. N.C. |
| 2. LOIN | 10. N.C. |
| 3. GND | 11. N.C. |
| 4. IInput | 12. MODOut |
| 5. TIInput | 13. GND |
| 6. Q Input | 14. GND |
| 7. Q Input | 15. VPS (Power Save) |
| 8. GND | 16. Vcc |

All dimensions are typical unless specified otherwise.

APPLICATION CIRCUIT



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